

L Number	Hits	Search Text	DB	Time stamp
1	1481	257/678.ccls.	USPAT; EPO; JPO; DERWENT	2004/04/26 14:07
2	1301	257/690.ccls.	USPAT; EPO; JPO; DERWENT	2004/04/26 14:07
3	1361	257/692.ccls.	USPAT; EPO; JPO; DERWENT	2004/04/26 14:07
4	720	257/727.ccls.	USPAT; EPO; JPO; DERWENT	2004/04/26 14:07
5	140238	mount\$5 near5 hole	USPAT; EPO; JPO; DERWENT	2004/04/26 14:20
6	431702	base near5 (plate or member)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:20
7	21315	(mount\$5 near5 hole) and (base near5 (plate or member))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:09
10	13	257/692.ccls. and ((mount\$5 near5 hole) and (base near5 (plate or member)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:09
11	15	257/727.ccls. and ((mount\$5 near5 hole) and (base near5 (plate or member)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:09
8	14	257/678.ccls. and ((mount\$5 near5 hole) and (base near5 (plate or member)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:09
9	11	257/690.ccls. and ((mount\$5 near5 hole) and (base near5 (plate or member)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:14
12	16962	vertical\$5 near leg	USPAT; EPO; JPO; DERWENT	2004/04/26 14:14
13	218	(mount\$5 near5 hole) same (vertical\$5 near leg)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:14
14	65	(base near5 (plate or member)) and ((mount\$5 near5 hole) same (vertical\$5 near leg))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:15
15	584823	semiconduct\$5 near5 device	USPAT; EPO; JPO; DERWENT	2004/04/26 14:15
16	1	((base near5 (plate or member)) and ((mount\$5 near5 hole) same (vertical\$5 near leg))) and (semiconduct\$5 near5 device)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:15

17	246991	257/\$.ccls.	USPAT; EPO; JPO; DERWENT	2004/04/26 14:16
18	1	257/\$.ccls. and ((base near5 (plate or member)) and ((mount\$5 near5 hole) same (vertical\$5 near leg)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:16
19	1	257/\$.ccls. and ((mount\$5 near5 hole) same (vertical\$5 near leg))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:16
20	54254	mount\$5 near5 leg	USPAT; EPO; JPO; DERWENT	2004/04/26 14:20
21	482716	base near5 (plate or member or substrate)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:20
22	10824	(mount\$5 near5 leg) and (base near5 (plate or member or substrate))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:21
23	2	257/678.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:21
24	2	257/690.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:21
25	1	257/692.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:22
26	6	257/727.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:22
27	60	257/\$.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:27
28	19	(257/\$.ccls. and ((mount\$5 near5 leg) and (base near5 (plate or member or substrate)))) and (semiconduct\$5 near5 device)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:30
29	9602	attach\$6 near5 stabiliz\$6	USPAT; EPO; JPO; DERWENT	2004/04/26 14:42
30	424	(mount\$5 near5 leg) and (attach\$6 near5 stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:30
31	1	(semiconduct\$5 near5 device) and ((mount\$5 near5 leg) and (attach\$6 near5 stabiliz\$6))	USPAT; EPO; JPO; DERWENT	2004/04/26 14:30
32	351	floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
33	0	257/678.ccls. and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31

34	0	257/690.ccls. and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
35	0	257/692.ccls. and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
36	0	257/727.ccls. and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
37	1	257/\$.ccls. and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
38	5	(semiconduct\$5 near5 device) and floatage	USPAT; EPO; JPO; DERWENT	2004/04/26 14:31
41	609795	stabiliz\$6	USPAT; EPO; JPO; DERWENT	2004/04/26 14:42
42	1457	((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6	USPAT; EPO; JPO; DERWENT	2004/04/26 14:42
43	15	(semiconduct\$5 near5 device) and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44
44	0	257/678.ccls. and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44
45	0	257/690.ccls. and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44
46	0	257/692.ccls. and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44
47	0	257/727.ccls. and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44
48	5	257/\$.ccls. and (((mount\$5 near5 leg) and (base near5 (plate or member or substrate))) and stabiliz\$6)	USPAT; EPO; JPO; DERWENT	2004/04/26 14:44